

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claim 1. (original) A multilayer ceramic electronic part having an external electrode(s) formed from a thermosetting conductive paste comprising conductive particles having a high melting point, metal powder having a melting point of 300 °C or less and a resin(s).

Claim 2. (original) The multilayer ceramic electronic part according to claim 1, wherein the total content of said conductive particles having a high melting point and said metal powder having a melting point of 300 °C or less in said thermosetting conductive paste is in the range of 70 to 95% by weight relative to the total weight of said conductive particles having a high melting point, said metal powder having a melting point of 300 °C or less, and said resin(s).

Claim 3. (currently amended) The multilayer ceramic electronic part according to claim 1 ~~or 2~~, wherein a content of said metal powder having a melting point of 300 °C or less in said thermosetting conductive paste is in the range of 5 to 20% by weight relative to the total weight of said conductive particles

having a high melting point and said metal powder having a melting point of 300 °C or less.

Claim 4. (original) A multilayer ceramic electronic part obtained according to a method comprising the steps of:

(1) providing a thermosetting conductive paste comprising conductive particles having a high melting point, metal powder having a melting point of 300 °C or less and a resin(s), and a ceramic composite body which is to be provided with an external electrode(s);

(2) printing or applying said thermosetting conductive paste on or to a surface(s) where an internal electrode(s) of said ceramic composite body is led out; and

(3) maintaining said ceramic composite body obtained in the step (2) at a temperature of 80 °C to 400 °C for a period of one to sixty minutes so as to form the external electrode(s).

Claim 5. (original) The multilayer ceramic electronic part according to claim 4, wherein said conductive particle in said external electrode(s) makes a diffused junction with a metal of said internal electrode(s) of said multilayer ceramic composite body.

Claim 6. (currently amended) The multilayer ceramic electronic part according to claim 4 ~~any one of claims 1 to 5~~, wherein said

multilayer ceramic electronic part is selected from the group consisting of a capacitor, a capacitor array, a thermistor, a varistor, an LC composite part, a CR composite part, an LR composite part, and an LCR composite part.

Claim 7. (new) The multilayer ceramic electronic part according to claim 2, wherein a content of said metal powder having a melting point of 300 °C or less in said thermosetting conductive paste is in the range of 5 to 20% by weight relative to the total weight of said conductive particles having a high melting point and said metal powder having a melting point of 300 °C or less.